



# CY7C10212CV33-12BAXET Status: In Production

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[Datasheet](#)  
[Quality and RoHS](#)  
[Support and Community](#)

[Inventory](#)  
[Technical Documents](#)

[Packaging/Ordering](#)  
[Related Products](#)



CY7C10212CV33-12BAXET	
Automotive Qualified	Y
Min. Operating Voltage (V)	3.00
Max. Operating Voltage (V)	3.60
Min. Operating Temp. (°C)	-40
Max. Operating Temp. (°C)	125
Frequency (MHz)	N/A
Temp. Classification	Automotive(E)
Max. Operating VCCQ (V)	3.60
Min. Operating VCCQ (V)	3.00
Speed (ns)	12
Density (Kb)	1024
Organization (X x Y)	64K x 16

Pricing & Inventory Availability			
1-10 unit Price*	11-100 unit Price*	101-1000 unit Price*	1001 + unit Price*
Availability	Quantity	Ships In	Order Now

\* Prices are shown in United States dollars and are for budgetary use only.

Packaging/Ordering	
Package	<a href="#">FBGA</a>
No. of Pins	48
Package Dimensions	275 L X 1.2 H X 275 W (Mils)
Package Weight	103.15 (mgs)
Package Cross Section Drawing	<a href="#">Download</a>
Package Carrier	REEL
Package Carrier Drawing / Orientation	<a href="#">Tape Drawing</a> , <a href="#">Reel Drawing</a> , <a href="#">Package Orientation</a>
Standard Pack Quantity	2000
Minimum Order Quantity (MOQ)	2000
Order Increment	2000
Estimated Lead Time (days)	42
HTS Code	8542.32.0040
ECCN	3A991

ECCN Suball	(B.2.B.)
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## Quality and RoHS

Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 ( <a href="#">Cypress Reflow Profile</a> )
RoHS Compliant	Y <a href="#">Print RoHS Certificate of Compliance</a>
PB Free	Y
Lead/Ball Finish	Sn/Ag/Cu
Marking	<a href="#">Cypress Marking Format</a>

### Package Material Declaration

048-BGA 7X7mm 001-04281 *Last Update: 06/25/2012*

### IPC 1752 Material Declaration

IPC-1752-2\_V1.1\_BGA 48 (7 X 7 MM) \_ASET\_SNAGCU *Last Update: 07/04/2012*

### RoHS Analysis Certificates (CoA)

[PACKAGE ROHS ANALYSIS REPORT - BGA \(BK/BP 36, 42, 48, 96\) \(BW 96,100,119,144,165,172,196,209,256,400\) USING MOLD COMPOUND KEG2270, ADHESIVE 2025D, SAC405 - ASE TAIWAN ASSEMBLY](#) *Last Update: 07/04/2012*

### Device Qualification Reports

 FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report. Please click [here](#).

## Technical Documents

### Application Notes (1)

[AN6081 - Interfacing 90-nm Cypress Asynchronous SRAMs in Legacy Systems](#) *Last Update: 19/12/2012*

### Product Information Notice (PIN) (1)

[PIN135200](#) *Last Update: 21/03/2013*

## Support and Community

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